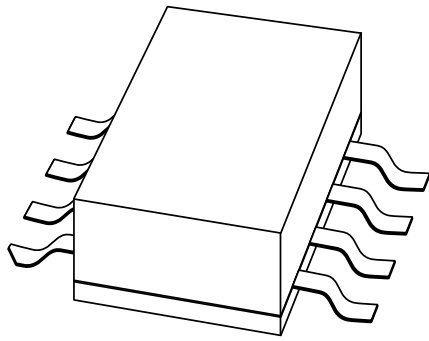


# DATA SHEET



## **BLV909** UHF power transistor

Product specification  
Supersedes data of 1996 Nov 04

1999 Jun 25

# UHF power transistor

# BLV909

### FEATURES

- Emitter ballasting resistors for optimum temperature profile
- Gold metallization ensures excellent reliability
- Internal input matching to achieve high power gain and easy design of wideband circuits.

### APPLICATIONS

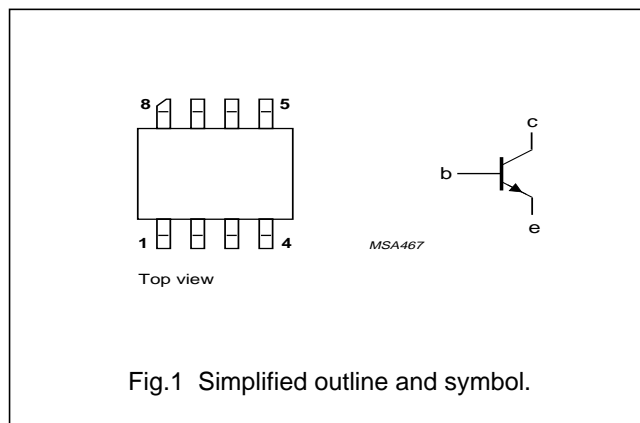
- Common emitter class-AB operation in base stations in the 820 to 960 MHz frequency range.

### DESCRIPTION

NPN silicon planar epitaxial transistor in an 8-lead SOT409B SMD package with a ceramic cap. All leads are isolated from the mounting base.

### PINNING - SOT409B

PIN	SYMBOL	DESCRIPTION
1, 4, 5, 8	e	emitter
2, 3	b	base
6, 7	c	collector



### QUICK REFERENCE DATA

RF performance at  $T_{mb} = 25\text{ °C}$  in a common emitter test circuit.

MODE OF OPERATION	f (MHz)	$V_{CE}$ (V)	$P_L$ (W)	$G_p$ (dB)	$\eta_c$ (%)	$d_{im}$ (dBc)
CW, class-AB	960	26	9	$\geq 9.5$	$\geq 50$	–
2-tone, class-AB	$f_1 = 960; f_2 = 960.1$	26	9 (PEP)	$\geq 9.5$	$\geq 35$	typ. -30

# UHF power transistor

# BLV909

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

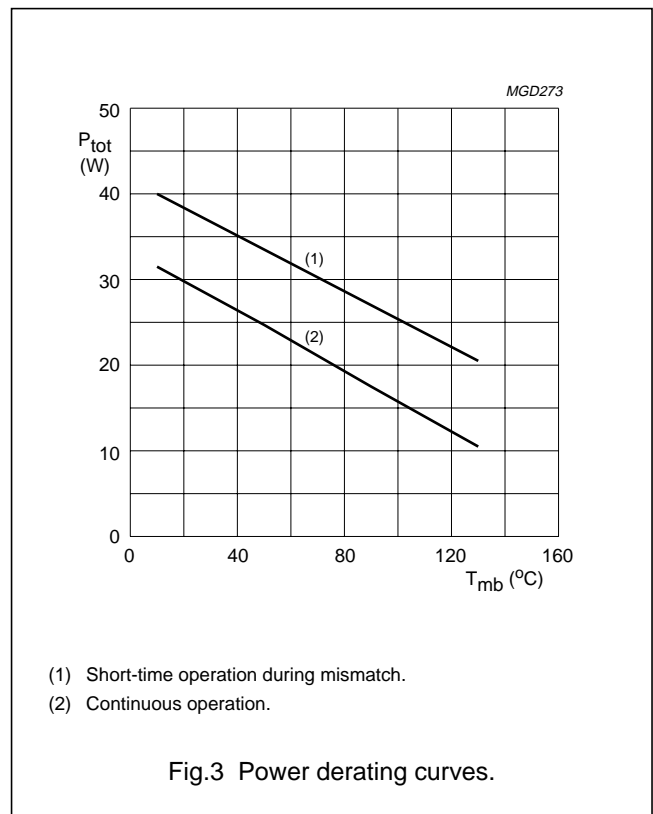
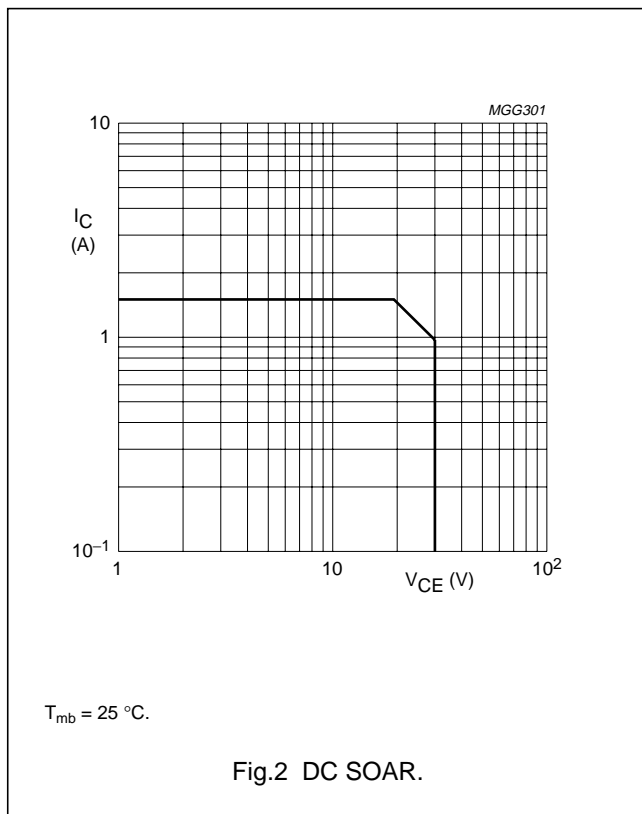
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$V_{CBO}$	collector-base voltage	open emitter	–	70	V
$V_{CEO}$	collector-emitter voltage	open base	–	30	V
$V_{EBO}$	emitter-base voltage	open collector	–	3	V
$I_C$	collector current (DC)		–	1.5	A
$I_{C(AV)}$	average collector current		–	1.5	A
$P_{tot}$	total power dissipation	$T_{mb} = 25\text{ °C}$ ; note 1	–	29	W
$T_{stg}$	storage temperature		–65	+150	°C
$T_j$	operating junction temperature		–	200	°C

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-mb}$	thermal resistance from junction to mounting base	$P_{tot} = 29\text{ W}$ ; $T_{mb} = 25\text{ °C}$ ; note 1	6	K/W

### Note to the Limiting values and Thermal characteristics

1. Transistor with metallized ground plane mounted on a printed-circuit board, see "Mounting and soldering section, Handbook SC19a."



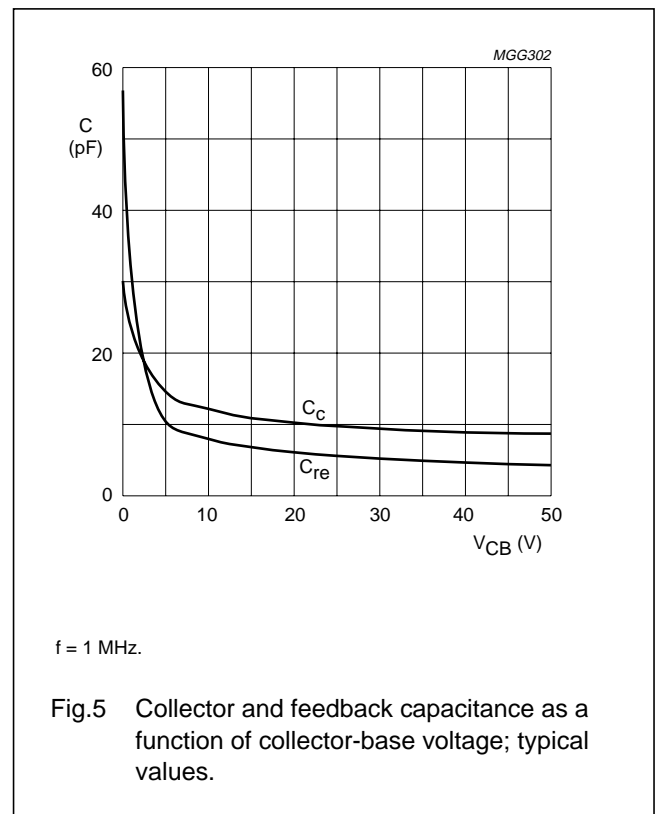
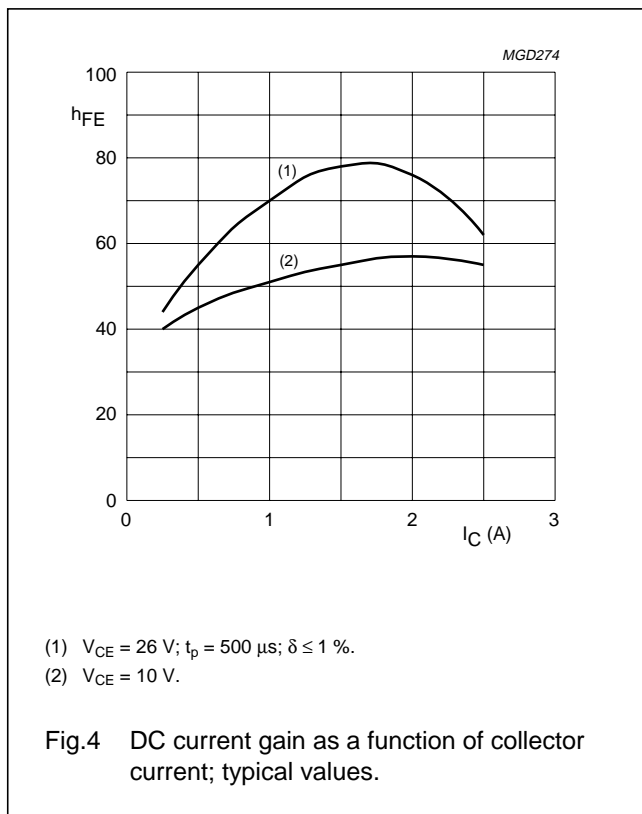
UHF power transistor

BLV909

**CHARACTERISTICS**

$T_j = 25\text{ }^\circ\text{C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$V_{(BR)CBO}$	collector-base breakdown voltage	open emitter; $I_C = 5\text{ mA}$	70	–	–	V
$V_{(BR)CEO}$	collector-emitter breakdown voltage	open base; $I_C = 15\text{ mA}$	30	–	–	V
$V_{(BR)EBO}$	emitter-base breakdown voltage	open collector; $I_E = 0.3\text{ mA}$	3	–	–	V
$I_{CES}$	collector leakage current	$V_{CE} = 28\text{ V}; V_{BE} = 0$	–	–	0.75	mA
$h_{FE}$	DC current gain	$V_{CE} = 10\text{ V}; I_C = 500\text{ mA}$	30	–	120	
$C_c$	collector capacitance	$V_{CB} = 26\text{ V}; I_E = i_e = 0; f = 1\text{ MHz}$	–	10	–	pF
$C_{re}$	feedback capacitance	$V_{CE} = 26\text{ V}; I_C = 0; f = 1\text{ MHz}$	–	6	–	pF



# UHF power transistor

# BLV909

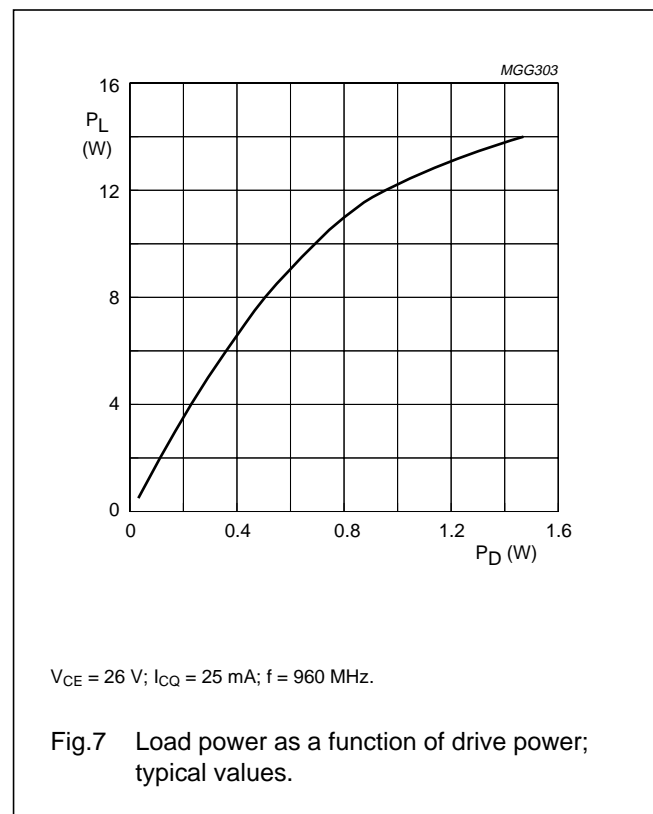
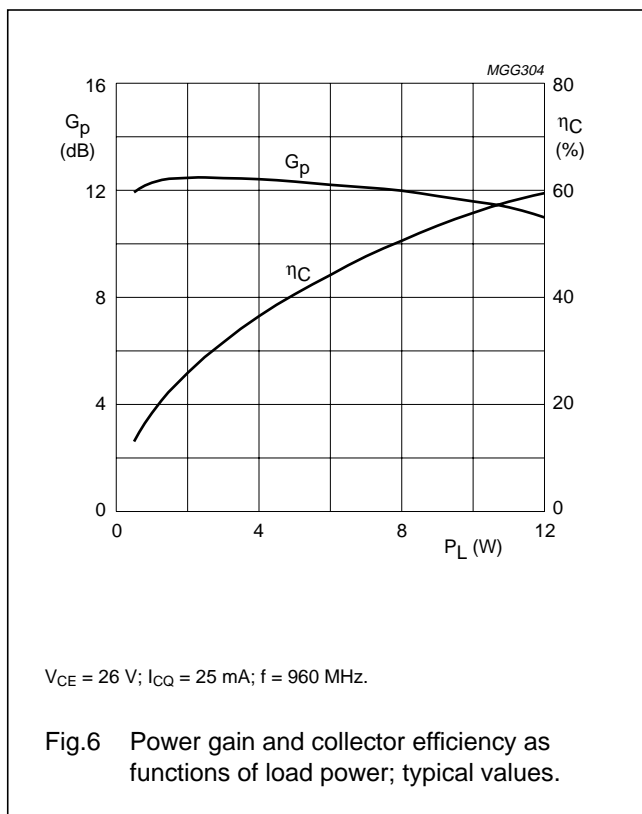
## APPLICATION INFORMATION

RF performance at  $T_{mb} = 25\text{ }^{\circ}\text{C}$  in a common emitter test circuit (see Figs 12 and 13).

MODE OF OPERATION	f (MHz)	V <sub>CE</sub> (V)	I <sub>CQ</sub> (mA)	P <sub>L</sub> (W)	G <sub>p</sub> (dB)	η <sub>c</sub> (%)	d <sub>im</sub> (dBc)
CW, class-AB	960	26	25	9	≥9.5, typ. 11.5	≥50, typ. 55	–
2-tone, class-AB	f <sub>1</sub> = 960; f <sub>2</sub> = 960.1	26	25	9 (PEP)	≥9.5, typ. 11.5	≥35, typ. 40	typ. –30

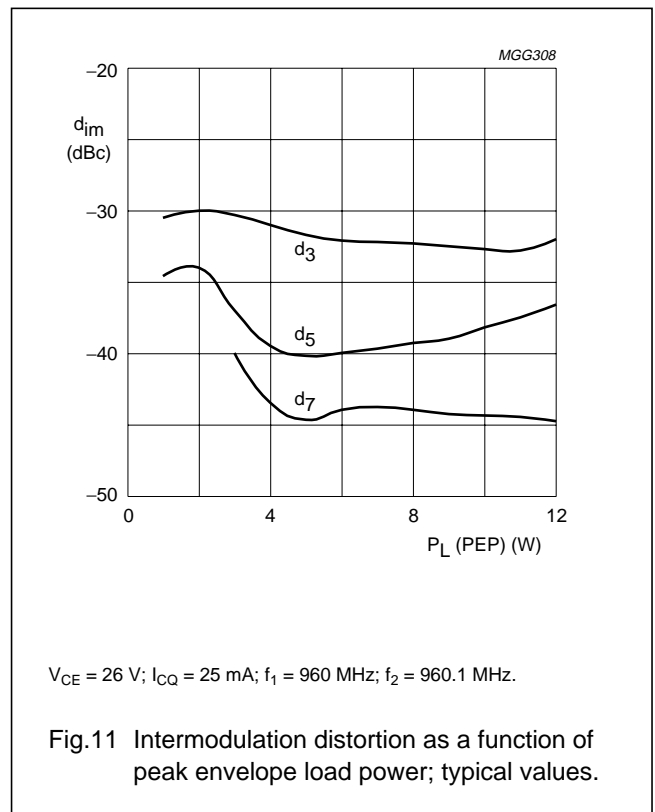
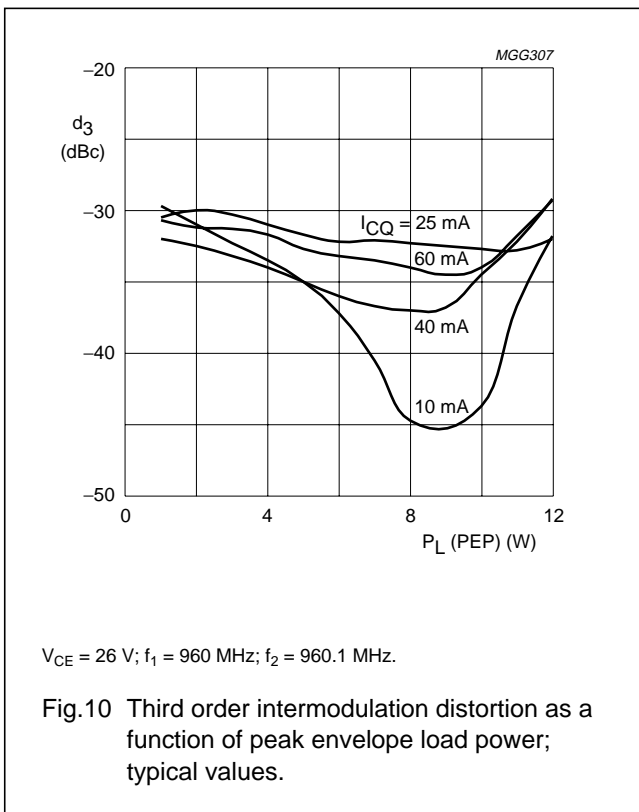
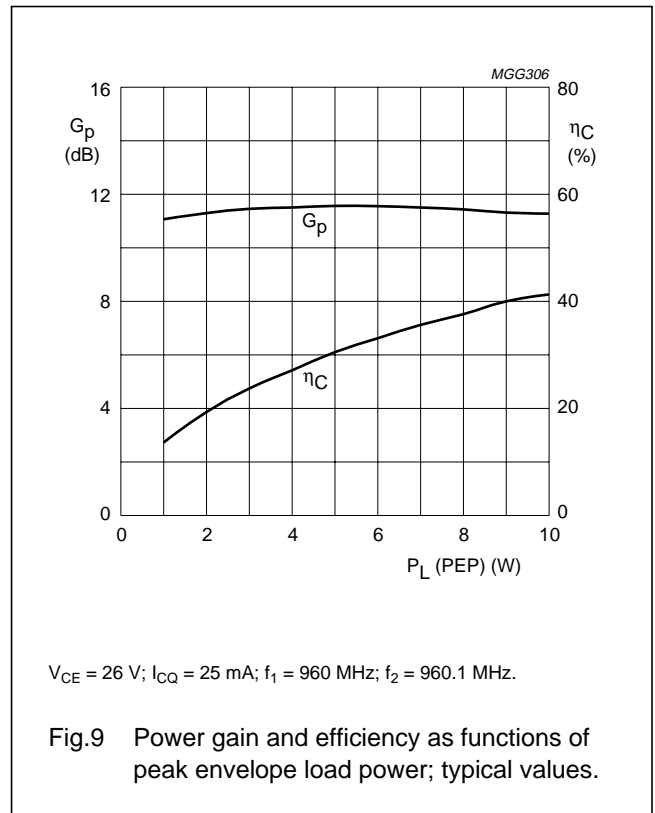
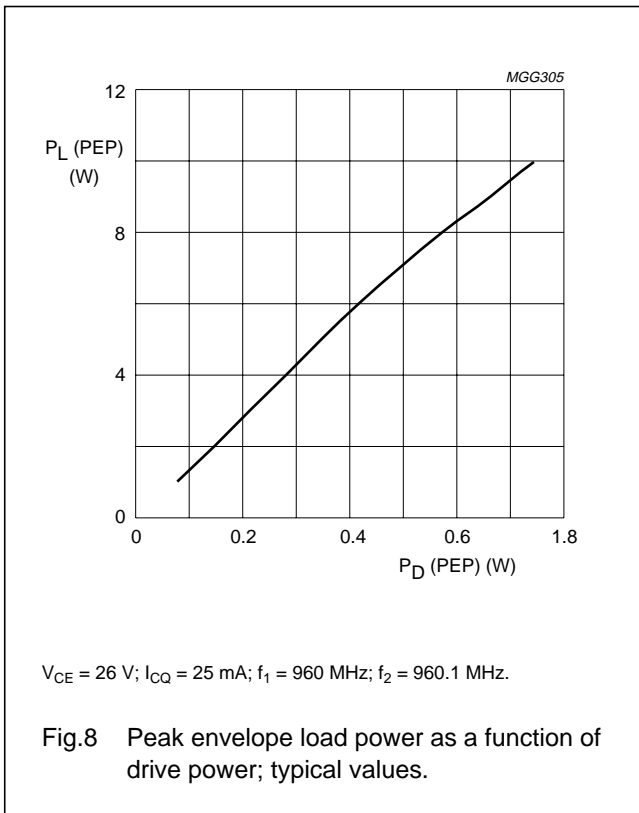
### Ruggedness in class-AB operation

The BLV909 is capable of withstanding a load mismatch corresponding to VSWR = 20 : 1 through all phases under the following conditions: f = 960 MHz; V<sub>CE</sub> = 26 V; I<sub>CQ</sub> = 25 mA; T<sub>mb</sub> = 25 °C.



UHF power transistor

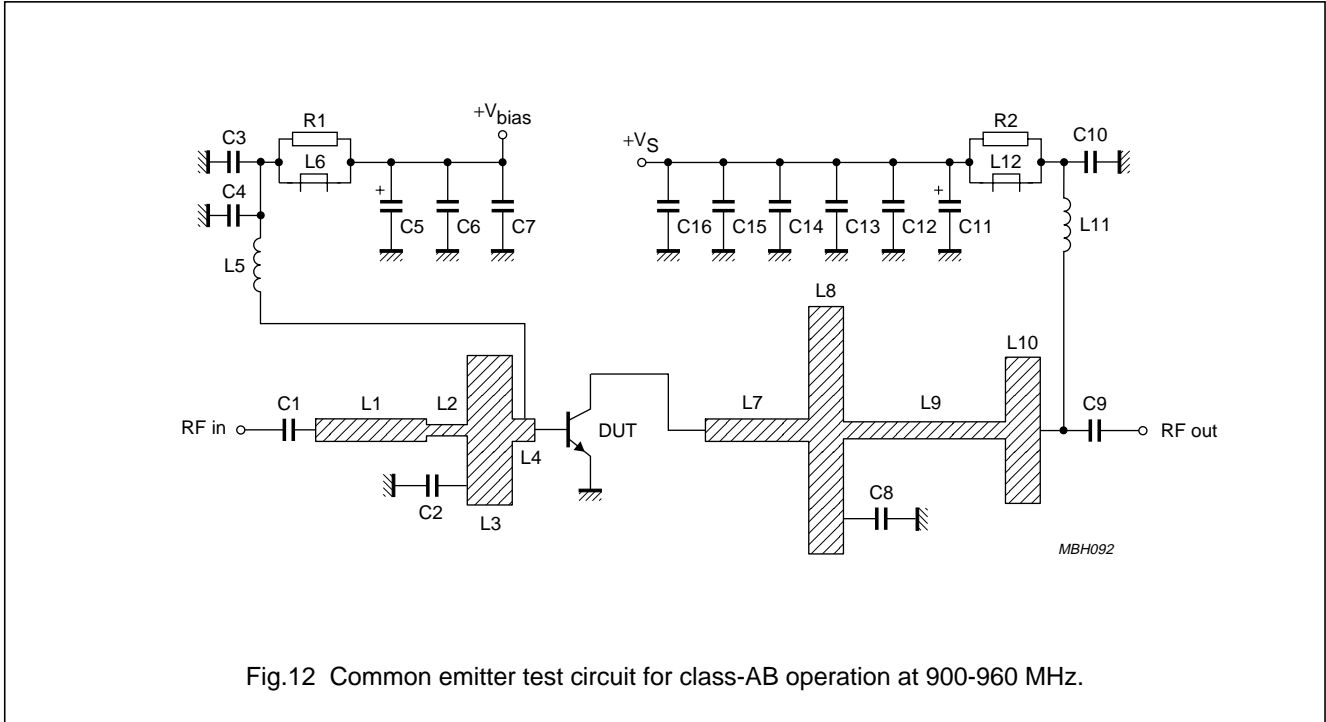
BLV909



UHF power transistor

BLV909

Test circuit information



Mounting recommendations

Both the metallized rear side and the leads of the device contribute to the heat flow. For the best results, it is recommended to mount the transistor on a grounded metallized area on the printed-circuit board, which is equipped with a large number of through metallized holes filled with solder.

When the heatsink is mounted to the rear side of the printed-circuit board by means of heatsink compound, a thermal resistance between the mounting base and the heatsink of 0.9 K/W can be achieved.

## UHF power transistor

BLV909

## List of components used in test circuit (see Figs 12 and 13)

COMPONENT	DESCRIPTION	VALUE	DIMENSIONS	CATALOGUE No.
C1, C9	multilayer ceramic chip capacitor; note 1	24 pF		
C2	multilayer ceramic chip capacitor; notes 1 and 2	5.6 pF		
C3, C7, C10, C16	multilayer ceramic chip capacitor; note 3	110 pF		
C4, C15	multilayer ceramic chip capacitor; note 3	200 pF		
C5, C11	tantalum SMD capacitor	10 $\mu$ F, 35 V		
C6, C12, C13, C14	ceramic chip capacitor	100 nF		2222 852 47104
C8	multilayer ceramic chip capacitor; note 1	8.2 pF		
L1	stripline; note 4	24.3 $\Omega$	length 9.85 mm width 2 mm	
L2	stripline; note 4	37.5 $\Omega$	length 3.63 mm width 1 mm	
L3	stripline; note 4	5.11 $\Omega$	length 4.1 mm width 13.3 mm	
L4	stripline; note 4	24.3 $\Omega$	length 2 mm width 2 mm	
L5	RF choke	0.22 $\mu$ H		
L6, L12	grade 4S2 ferroxcube chip-bead			
L7	stripline; note 4	24.3 $\Omega$	length 9.2 mm width 2 mm	
L8	stripline; note 4	3.2 $\Omega$	length 3.1 mm width 22 mm	
L9	stripline; note 4	29.4 $\Omega$	length 14.4 mm width 1.5 mm	
L10	stripline; note 4	5.22 $\Omega$	length 3.2 mm width 13 mm	
L11	5 turns enamelled 1 mm copper wire	35 nH	pitch 1.23 mm int. dia. 3.2 mm	
R1, R2	metal film resistor	100 $\Omega$ , 0.4 W		

## Notes

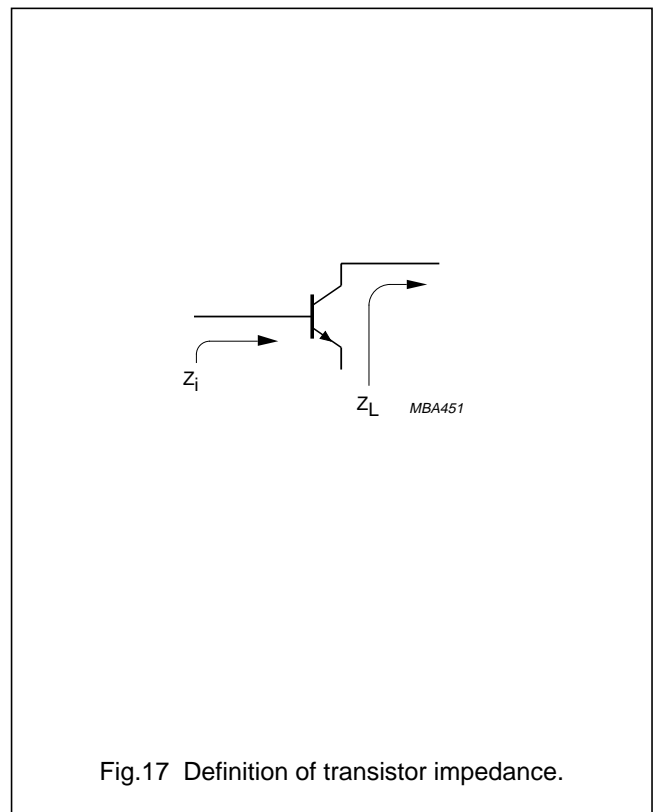
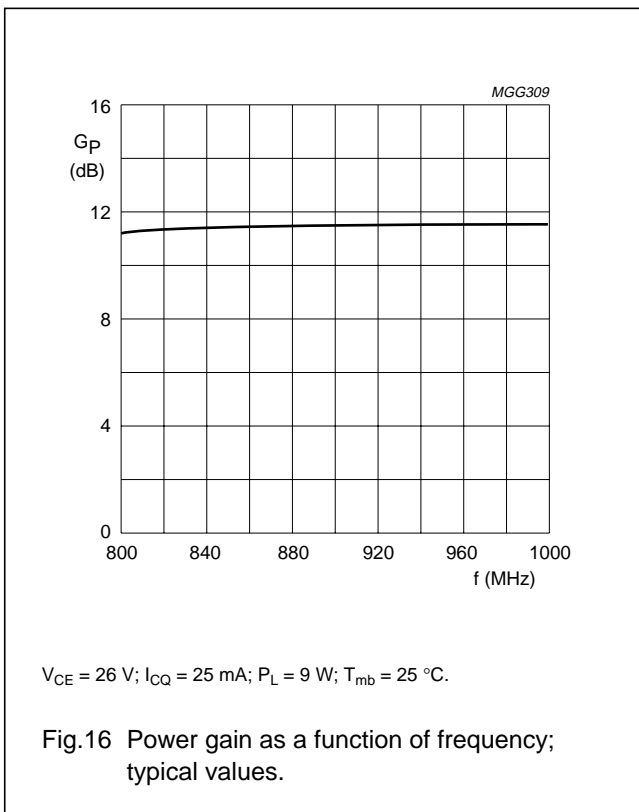
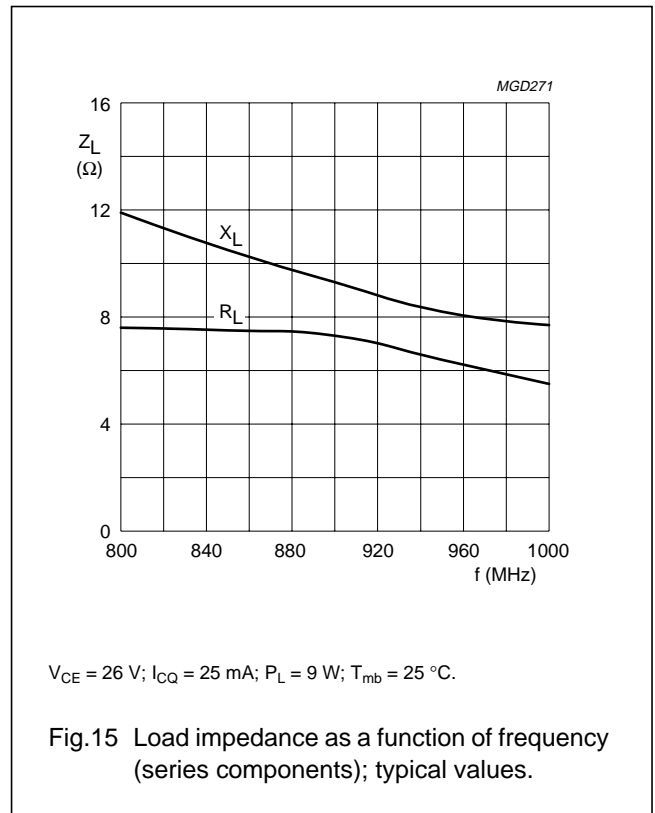
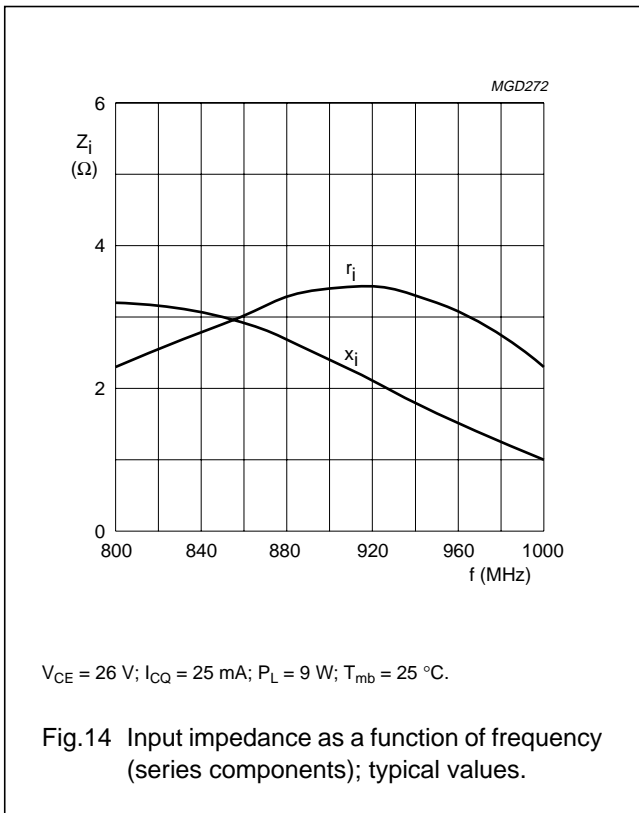
- American Technical Ceramics type 100A or capacitor of same quality.
- For operation at 820 to 900 MHz: C2 = 6.2 pF.
- American Technical Ceramics type 100B or capacitor of same quality.
- The striplines are on a double copper-clad printed-circuit board, with PTFE fibre-glass dielectric ( $\epsilon_r = 10.2$ ); thickness 0.64 mm.





UHF power transistor

BLV909



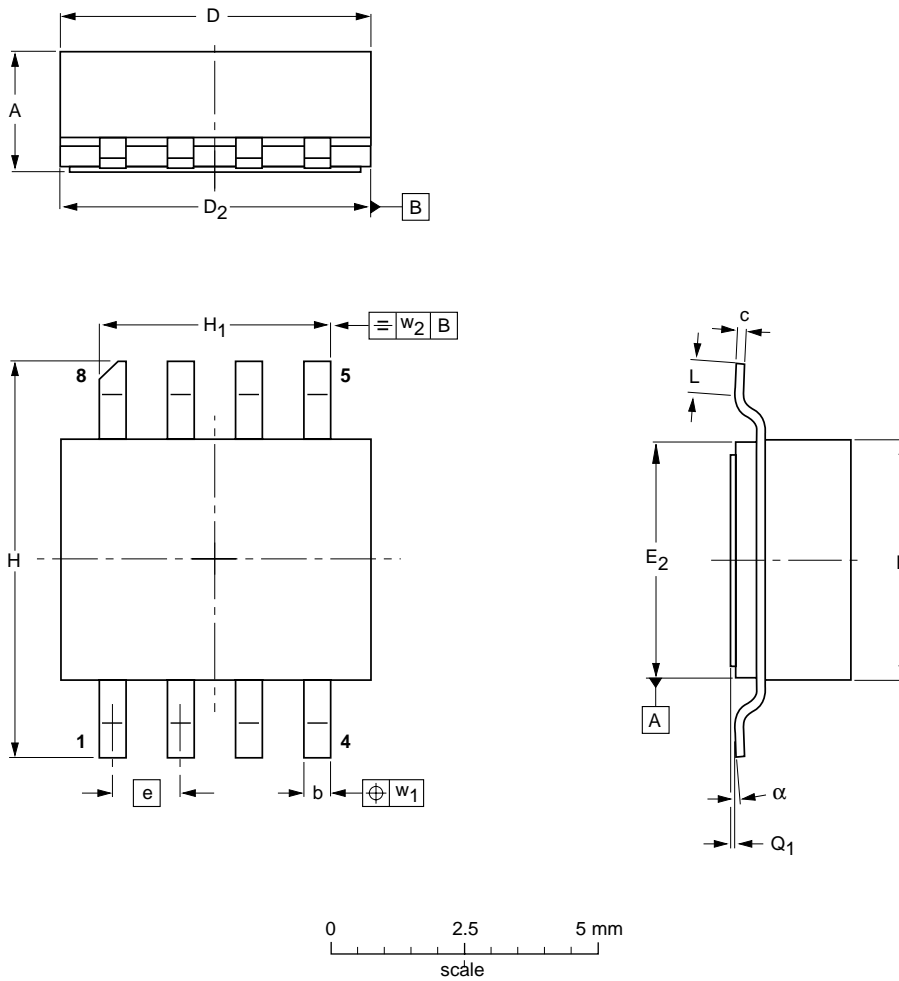
UHF power transistor

BLV909

PACKAGE OUTLINE

Ceramic surface mounted package; 8 leads

SOT409B



DIMENSIONS (millimetre dimensions are derived from the original inch dimensions)

UNIT	A	b	c	D	D <sub>2</sub>	E	E <sub>2</sub>	e	H	H <sub>1</sub>	L	Q <sub>1</sub>	w <sub>1</sub>	w <sub>2</sub>	$\alpha$
mm	2.36 2.06	0.58 0.43	0.15 0.10	5.94 5.03	5.16 5.00	4.93 4.01	4.14 3.99	1.27	7.47 7.26	4.39 4.24	0.84 0.69	0.10 0.00	0.25	0.25	2° 0°
inches	0.093 0.081	0.023 0.017	0.006 0.004	0.234 0.198	0.203 0.197	0.194 0.158	0.163 0.157	0.050	0.294 0.286	0.173 0.167	0.033 0.027	0.004 0.000	0.010	0.010	2° 0°

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT409B						98-01-27

## UHF power transistor

BLV909

**DEFINITIONS**

<b>Data Sheet Status</b>	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
<b>Limiting values</b>	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
<b>Application information</b>	
Where application information is given, it is advisory and does not form part of the specification.	

**LIFE SUPPORT APPLICATIONS**

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

UHF power transistor

BLV909

---

**NOTES**

UHF power transistor

BLV909

---

**NOTES**

UHF power transistor

BLV909

---

**NOTES**

# Philips Semiconductors – a worldwide company

**Argentina:** see South America

**Australia:** 34 Waterloo Road, NORTH RYDE, NSW 2113,  
Tel. +61 2 9805 4455, Fax. +61 2 9805 4466

**Austria:** Computerstr. 6, A-1101 WIEN, P.O. Box 213,  
Tel. +43 1 60 101 1248, Fax. +43 1 60 101 1210

**Belarus:** Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6,  
220050 MINSK, Tel. +375 172 20 0733, Fax. +375 172 20 0773

**Belgium:** see The Netherlands

**Brazil:** see South America

**Bulgaria:** Philips Bulgaria Ltd., Energoproject, 15th floor,  
51 James Bourchier Blvd., 1407 SOFIA,  
Tel. +359 2 68 9211, Fax. +359 2 68 9102

**Canada:** PHILIPS SEMICONDUCTORS/COMPONENTS,  
Tel. +1 800 234 7381, Fax. +1 800 943 0087

**China/Hong Kong:** 501 Hong Kong Industrial Technology Centre,  
72 Tat Chee Avenue, Kowloon Tong, HONG KONG,  
Tel. +852 2319 7888, Fax. +852 2319 7700

**Colombia:** see South America

**Czech Republic:** see Austria

**Denmark:** Sydhavnsgade 23, 1780 COPENHAGEN V,  
Tel. +45 33 29 3333, Fax. +45 33 29 3905

**Finland:** Sinikalliontie 3, FIN-02630 ESPOO,  
Tel. +358 9 615 800, Fax. +358 9 6158 0920

**France:** 51 Rue Carnot, BP317, 92156 SURESNES Cedex,  
Tel. +33 1 4099 6161, Fax. +33 1 4099 6427

**Germany:** Hammerbrookstraße 69, D-20097 HAMBURG,  
Tel. +49 40 2353 60, Fax. +49 40 2353 6300

**Hungary:** see Austria

**India:** Philips INDIA Ltd, Band Box Building, 2nd floor,  
254-D, Dr. Annie Besant Road, Worli, MUMBAI 400 025,  
Tel. +91 22 493 8541, Fax. +91 22 493 0966

**Indonesia:** PT Philips Development Corporation, Semiconductors Division,  
Gedung Philips, Jl. Buncit Raya Kav.99-100, JAKARTA 12510,  
Tel. +62 21 794 0040 ext. 2501, Fax. +62 21 794 0080

**Ireland:** Newstead, Clonskeagh, DUBLIN 14,  
Tel. +353 1 7640 000, Fax. +353 1 7640 200

**Israel:** RAPAC Electronics, 7 Kehilat Saloniki St, PO Box 18053,  
TEL AVIV 61180, Tel. +972 3 645 0444, Fax. +972 3 649 1007

**Italy:** PHILIPS SEMICONDUCTORS, Piazza IV Novembre 3,  
20124 MILANO, Tel. +39 02 67 52 2531, Fax. +39 02 67 52 2557

**Japan:** Philips Bldg 13-37, Kohnan 2-chome, Minato-ku,  
TOKYO 108-8507, Tel. +81 3 3740 5130, Fax. +81 3 3740 5057

**Korea:** Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL,  
Tel. +82 2 709 1412, Fax. +82 2 709 1415

**Malaysia:** No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR,  
Tel. +60 3 750 5214, Fax. +60 3 757 4880

**Mexico:** 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,  
Tel. +9-5 800 234 7381, Fax +9-5 800 943 0087

**Middle East:** see Italy

**Netherlands:** Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,  
Tel. +31 40 27 82785, Fax. +31 40 27 88399

**New Zealand:** 2 Wagener Place, C.P.O. Box 1041, AUCKLAND,  
Tel. +64 9 849 4160, Fax. +64 9 849 7811

**Norway:** Box 1, Manglerud 0612, OSLO,  
Tel. +47 22 74 8000, Fax. +47 22 74 8341

**Pakistan:** see Singapore

**Philippines:** Philips Semiconductors Philippines Inc.,  
106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI,  
Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

**Poland:** Ul. Lukiska 10, PL 04-123 WARSZAWA,  
Tel. +48 22 612 2831, Fax. +48 22 612 2327

**Portugal:** see Spain

**Romania:** see Italy

**Russia:** Philips Russia, Ul. Usatcheva 35A, 119048 MOSCOW,  
Tel. +7 095 755 6918, Fax. +7 095 755 6919

**Singapore:** Lorong 1, Toa Payoh, SINGAPORE 319762,  
Tel. +65 350 2538, Fax. +65 251 6500

**Slovakia:** see Austria

**Slovenia:** see Italy

**South Africa:** S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale,  
2092 JOHANNESBURG, P.O. Box 58088 Newville 2114,  
Tel. +27 11 471 5401, Fax. +27 11 471 5398

**South America:** Al. Vicente Pinzon, 173, 6th floor,  
04547-130 SÃO PAULO, SP, Brazil,  
Tel. +55 11 821 2333, Fax. +55 11 821 2382

**Spain:** Balmes 22, 08007 BARCELONA,  
Tel. +34 93 301 6312, Fax. +34 93 301 4107

**Sweden:** Kottbygatan 7, Akalla, S-16485 STOCKHOLM,  
Tel. +46 8 5985 2000, Fax. +46 8 5985 2745

**Switzerland:** Allmendstrasse 140, CH-8027 ZÜRICH,  
Tel. +41 1 488 2741 Fax. +41 1 488 3263

**Taiwan:** Philips Semiconductors, 6F, No. 96, Chien Kuo N. Rd., Sec. 1,  
TAIPEI, Taiwan Tel. +886 2 2134 2886, Fax. +886 2 2134 2874

**Thailand:** PHILIPS ELECTRONICS (THAILAND) Ltd.,  
209/2 Sanpavuth-Bangna Road Prakanong, BANGKOK 10260,  
Tel. +66 2 745 4090, Fax. +66 2 398 0793

**Turkey:** Yukari Dudullu, Org. San. Blg., 2.Cad. Nr. 28 81260 Umraniye,  
ISTANBUL, Tel. +90 216 522 1500, Fax. +90 216 522 1813

**Ukraine:** PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7,  
252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

**United Kingdom:** Philips Semiconductors Ltd., 276 Bath Road, Hayes,  
MIDDLESEX UB3 5BX, Tel. +44 208 730 5000, Fax. +44 208 754 8421

**United States:** 811 East Arques Avenue, SUNNYVALE, CA 94088-3409,  
Tel. +1 800 234 7381, Fax. +1 800 943 0087

**Uruguay:** see South America

**Vietnam:** see Singapore

**Yugoslavia:** PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD,  
Tel. +381 11 62 5344, Fax.+381 11 63 5777

**For all other countries apply to:** Philips Semiconductors,  
International Marketing & Sales Communications, Building BE-p, P.O. Box 218,  
5600 MD EINDHOVEN, The Netherlands, Fax. +31 40 27 24825

**Internet:** <http://www.semiconductors.philips.com>

© Philips Electronics N.V. 1999

SCA 66

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Printed in The Netherlands

125002/03/pp16

Date of release: 1999 Jun 25

Document order number: 9397 750 05707

*Let's make things better.*

**Philips**  
Semiconductors



**PHILIPS**